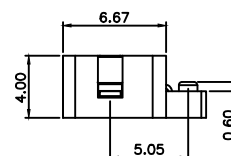
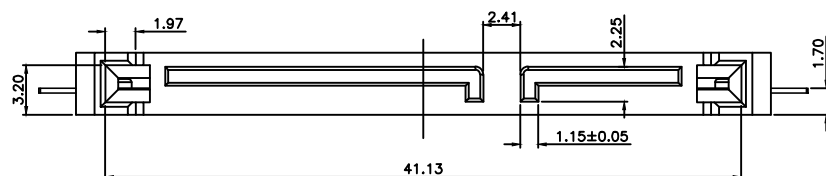
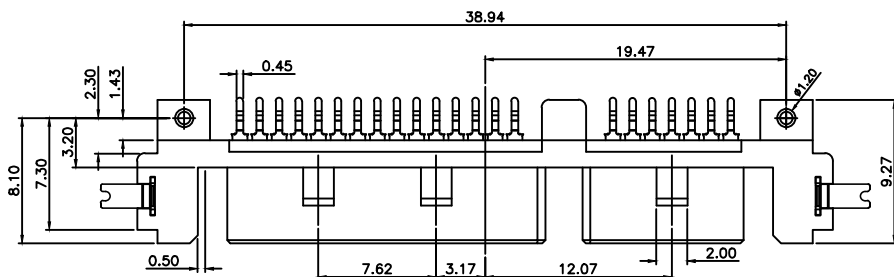
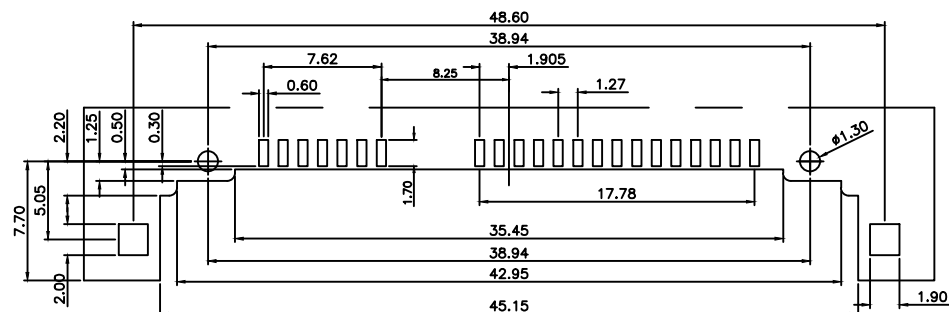
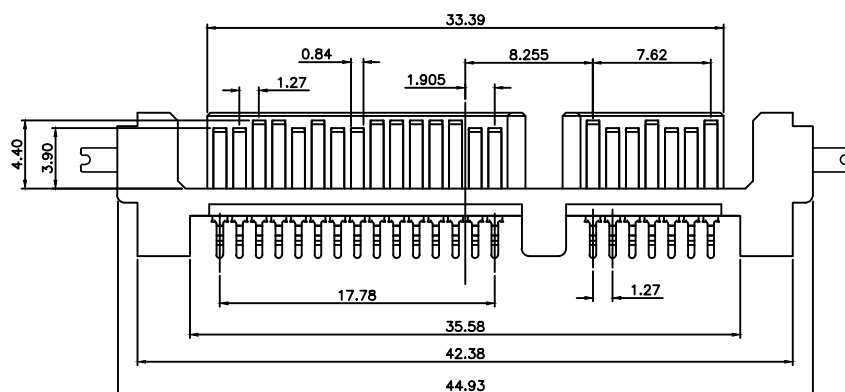


GP Component

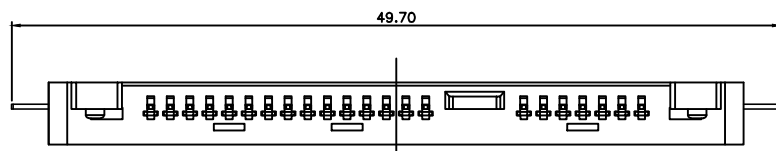
REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2013/1/16	Jamie Zie



NOTES:
 1.MATERIAL:
 HOUSING:LCP G/F UL94 V-0
 COLOR:BLACK
 CONTACT:BRASS T=0.25mm
 PEG:BRASS T=0.20mm
 2.FINISH:
 CONTACT:GOLD FLASH/TIN PLATING ON CONTACT AREA
 100u" MIN.TIN PLATING ON SOLDERTAILS
 50u" MIN.NICKEL UNDERPLATING OVER ALL
 PEG:100u"MIN.TIN PLATION ON SOLDERTAILS
 50u"MIN.TIN NICKEL UNDERPLATING OVER ALL



RECOMMENDED P.C. B LAYOUT
 THICKNESS=1.0mm



NO	VARIETY	QTY	MATERIAL	REMARK
Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ±0.38 X:XX ±0.30 X:XXX ±0.25 X±3'		DESIGN BY : Jamie Zie	DATE : 2013/1/16	PART NAME: 7 +15 P male Shen plate SMT type
		CHECKED BY: David Chou	DATE : 2013/1/16	PART NO. MST22-01-07
		APPROVED BY1: Richard Hsieh	DATE : 2013/1/16	MOLD NO. N/A
		APPROVED BY2: Richard Hsieh	DATE : 2013/1/16	DRAW NO. AO
		SCALE:1:1	SIZE:A4	SHEET NO. 1 OF 1